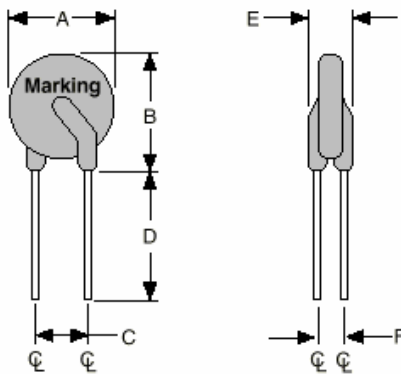


Features

- Radial leaded devices, higher rated voltage of 75V
- Cured, flame retardant epoxy polymer insulating material meets UL94 V-0 requirements
- Lead-free and compliant with the European Union RoHS Directive 2011/65/EU

Product Dimensions (mm)

Part number	A		B		C		D	E	F	Lead
	Max.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Typ.	Size(φ)
HL75-250F	21.3	23.5	9.5	10.9	7.6	3.1	1.4	0.8		



Electrical Characteristics

Part number	I_H (A)	I_T (A)	Max. Time-to-trip		V_{max} (V)	I_{max} (A)	Pd_{typ} (W)	R_{min} (Ω)	R_{max} (Ω)	R_{1max} (Ω)
			Current(A)	Time(s)						
HL75-250F	2.50	5.00	12.5	15.6	75	40	2.50	0.05	0.08	0.13

I_H =Hold current: maximum current at which the device will not trip at 25°C still air.

I_T =Trip current: minimum current at which the device will always trip at 25°C still air.

V_{max} =Maximum voltage device can withstand without damage at rated current.

I_{max} =Maximum fault current device can withstand without damage at rated voltage.

Max. Time-to-trip =Maximum time to trip(s) at assigned current.

Pd_{typ} =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min} =Minimum device resistance at 25°C prior to tripping.

R_{max} =Maximum device resistance at 25°C prior to tripping.

R_{1max} = Maximum resistance of device when measured one hour post trip at 25°C.

Thermal Derating Chart- I_H (A)

Part number	Maximum ambient operating temperatures(°C)								
	-40	-20	0	25	40	50	60	70	85
HL75-250F	4.05	3.58	3.02	2.50	2.02	1.80	1.55	1.30	0.90

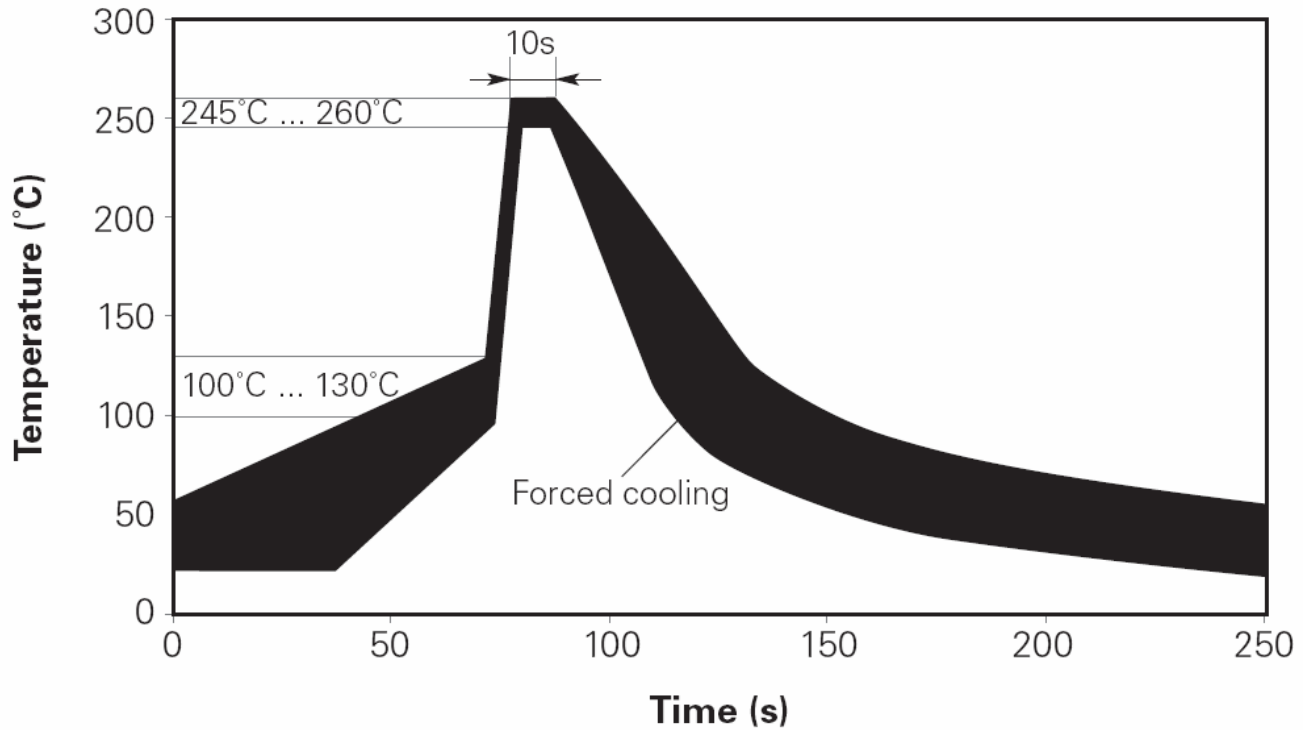
Package Information

Bulk: 500pcs per bag.

Specifications are subject to change without notice.

Soldering Recommendations

Wave Soldering



Hand Soldering

Soldering temperature: $350^{\circ}\text{C} \pm 5^{\circ}\text{C}$.

Soldering time: no more than 5s.

Soldering position: at least 4 mm away from PTC chip.